

ABSTRACT

ELECTRONIC CIRCUIT, METHOD FOR FORMING SAME, AND COPPER CLAD
LAMINATE FOR FORMING ELECTRONIC CIRCUIT

5 [Abstract]

10 Provided is an electronic circuit as a laminated body configured from a layer (A) which is made of a copper or copper alloy foil formed on one surface or both surfaces of a resin substrate, a copper or copper alloy plated layer (B) formed on a part or whole surface of the (A) layer, a plated layer (C) formed on a part or whole surface of the (B) layer and having a slower etching rate than that of copper relative to a copper etching solution, and a copper or copper alloy plated layer (D) formed on the layer (C) and which has a thickness of 0.05 μm or more and less than 1 μm , and which is made of a copper circuit formed by etching and removing a part of the laminated portion of the (A) layer, the (B) layer, the (C) layer and the (D) layer up to the resin substrate surface. It is thereby possible to form a circuit having a uniform circuit width, improve the etching properties in pattern etching, and prevent the occurrence of short-circuits and defects in the circuit width.

20 Fig. 1